Minutes IEEE P802.3cy Greater than 10 Gb/s Electrical Automotive Ethernet PHY TF AdHoc meeting April 27, 2021

Prepared by Natalie Wienckowski

Proposed Agenda:

Title	Presenters(s)	Affiliation(s)
Agenda	Natalie Wienckowski (ad hoc Chair)	General Motors
TF Chair's Comments	Steve Carlson	High Speed Design, Robert Bosch GmbH, Ethernovia
P802.3cy PCB and test Fixture Considerations	Chris DiMinico Haysam Kadry	MC Communications, PHY-SI LLC, SenTeske Ford
P802.3cy To-do list	Natalie Wienckowski	General Motors
Closing Remarks	Steve Carlson	High Speed Design, Robert Bosch GmbH, Ethernovia

See adhoc webpage for agenda deck and presentations

Agenda/Admin Natalie Wienckowski as ad hoc chair:

Meeting began at 10:08 am ET.

Introductions & Affiliations.

Presented file: cy_Task_Force_adhoc_agenda_04_27_21.pdf

1. Reviewed the Attendance information related to the ad hoc.
2. Displayed patent slide deck and asked if any participant had not read the IEEE-SA Patent Slides slide set, none responded.
   Call for Patents was made at 10:14 am Eastern Time, none responded
3. Displayed the IEEE-SA Copyright policy slide and asked if any participant had not read the IEEE copyright slide set, none responded.
4. Displayed the IEEE-SA Participation slide and reviewed it.
5. Reminded participants to indicate full names and employer/affiliation for the meeting minutes.

Instructions for subscribing to the reflector may be found at http://www.ieee802.org/3/cy/reflector.html. If you cannot subscribe to the reflector for some reason, and need additional assistance please contact the Task Force chair.

Chair's comments: None at this time.

Presentations/Discussion:

Presentation: P802.3cy PCB and test Fixture Considerations (Chris DiMinico/ MC Communications, PHY-SI LLC, SenTeske; Haysam Kadry/Ford)

Chris presented on PCB IL and Test Fixture Considerations. He provided some background definitions and information on what has been done in other projects. He then provided a proposed PCB IL budget assuming 3" of PCB trace. 0.45 power was used as it represents the "belly" at low frequencies that the material performance measurements shows.

The PCB material is the 526 shown in Haysam's presentation from March 1st. (PCB INSERTION LOSS MATERIAL COMPARISON)

Presentation: P802.3cy To-do list usage (Natalie Wienckowski, General Motors)

The to-do list was reviewed and updated. Participants are urged to review the list for topics they can support and for missing topics. Please send a message to the reflector with requested changes to the list.

The current list can be found on this page: To Do spreadsheets

Closing Discussion

The meeting on May 4th is cancelled as there are no topics planned for that day and none are anticipated.

The May 25th ad hoc meeting has been changed to an Interim.

Details for the IEEE 802.3 May Interim are available in the agenda.

Thanks to everyone, especially Haysam and Chris, for all their hard work.

Meeting adjourned at 11:17 AM ET.

Attendees (download participant list, email)

First	Last	Affiliation
Brett	McClellan	Marvell
Chris	DiMinico	MC Communications, PHY-SI, SenTekse / Panduit
Christian	Neulinger	MD Elektronik
Clark	Carty	Cisco
Cliff	Fung	Marvell
Dan	Kennefick	Daikin America
Dave	Hess	Cord Data
Eric J	Chang	Intel Corporation
Eric	DiBiaso	TE Connectivity
Erwin	Köeppendörfer	Leoni Kabel GmbH
Fred	Dawson	Chemours
George	Zimmerman	CME Consulting / ADI, APL Group, Cisco Systems, CommScope, Marvell, SenTekSe
Harsh	Patel	Molex
Haysam	Kadry	Ford
Hossein	Sedarat	Ethernovia
Istvan	BakroNagy	EFFECT Photonics
Jae-yong	Chang	Keysight
Jamila	Borda	BMW
Jim	Graba	Broadcom
Keisuke	Kawahara	FURUKAWA ELECTRIC
Ken	Scherzinger	CCC
Larry	McMillan	Western Digital
Louise	Yi	FIT
Makoto	Nariya	Sony
Manabu	Kagami	NITech (Nagoya Institute of Technology)
Mike	Tu	Broadcom
Natalie	Wienckowski	General Motors
Nobuyasu	Araki	Yazaki
Patrick	Casher	Foxconn Interconnect Technology
Pavel	Zivny	Tektronix
Peter	Wu	Marvell
Ragnar	Jonsson	Marvell
Rich	Boyer	Aptiv
Shao-Chieh	Yu	FIT
Shaowu	Huang	Marvell
Stefan	Gianordoli	GG Group

First	Last	Affiliation
Steve	Carlson	High Speed Design, Robert Bosch GmbH, Ethernovia
Taiji	Kondo	MegaChips
Terry	Little	Foxconn Interconnect Technology
Thomas	Müller	Rosenberger
Toshihiro	Ichimaru	Sumitomo
Yoshihiro	Niihara	Fujikura Ltd.
TOTAL	**42**	**Attendees**